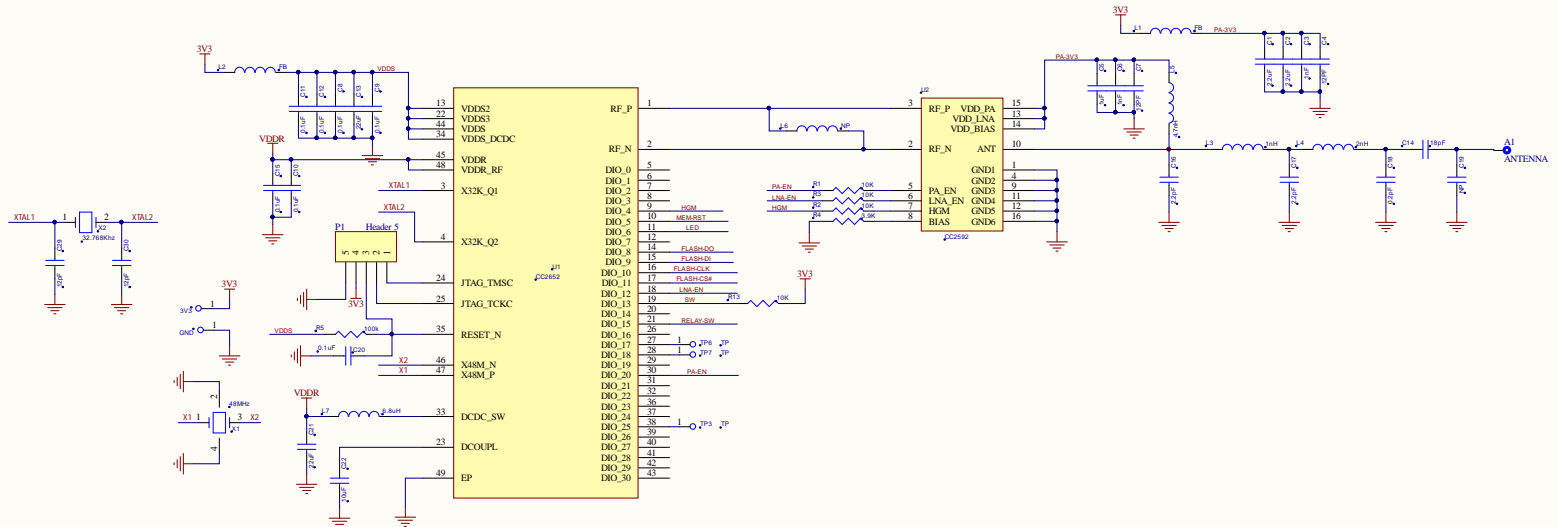
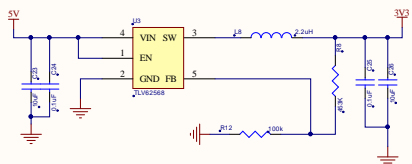


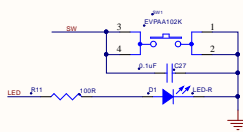
# CONTROLLER + ZIGBEE



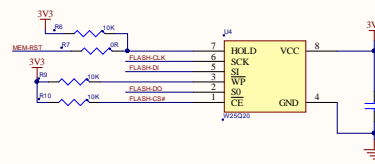
## 3V3 REGULATOR



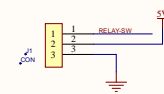
## SWITCH & LED



## FLASH



## INTERFACE CON



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
▽	2	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
□	8	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
○	80	0.250mm (9.84mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	90 Total						

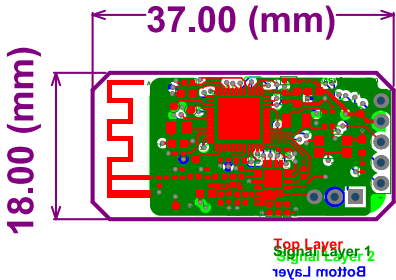
**FAB NOTES:**

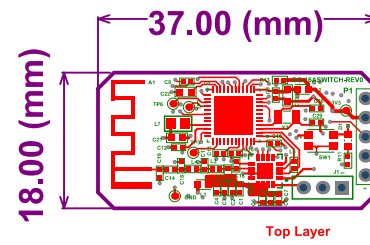
**Notes : UNLESS OTHER SPECIFIED**

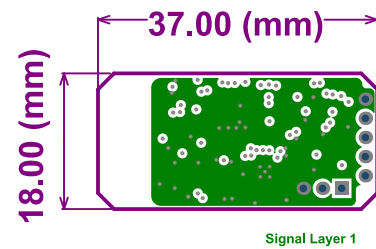
- 1. FABRICATON, DIMENSIONS, TOLERANCE, AS PER IPC-6012A & IPC- 2222 CLASS 2.  
 ALL VIEWS ARE SHOWN FROM TOP SIDE UNLESS OTHERWISE SPECIFIED.  
 PCB SIZE: 37mm X 18mm  
 LAYERS: 4  
 PCB THICKNESS: 1MM

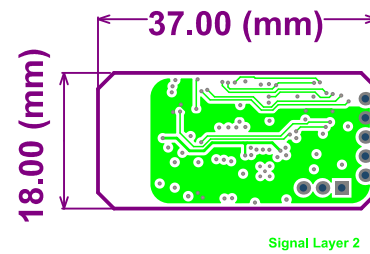
- 2. SURFACE FINISH: LEAD FREE HASL  
 PLATING REQUIREMENT:  
 START COPPER THICKNESS: 17 MICRON  
 FINISH COPPER THICKNESS: 35 MICRON  
 INNER COPPER THICKNESS: 35 MICRON

- 3. MATERIAL: FR-4
- 4. SOLDERMASK ON BOTH SIDES OF BOARD SHALL BE LPI, COLOR GREEN.
- 5. SILK SCREEN LEGEND TO BE APPLIED AS PER LAYER STACKUP USING WHITE NON-CONDUCTIVE EPOXY INK. COLOR WHITE.
- 6. ALL VIAS ARE TENTED ON BOTH SIDES UNLESS SPECIFIED SOLDERMASK OPEN IN GERBER.
- 7.GERBER SHOULD BE VERIFIED FOR 100% CONTINUITY AND SHORTS TESTING STRICTLY USING IPC-D-356A NETLIST.
- 8. VENDOR SHOULD FOLLOW ROHS3 COMPLIANT PROCESS AND Pb FREE MANUFACTURING.
- 9. MANUFACTURER'S IDENTIFICATIONS, DATECODE LETTER SHALL BE IN SILKSCREEN ON SOLDER SIDE OF BOARD.
- 10. WARP AND TWIST SHALL NOT EXCEED 0.007 in. PER INCH/INCH LINEAR.
- 11. 9,18 mil trace width in TOP layer for 50 ohm Impedance.

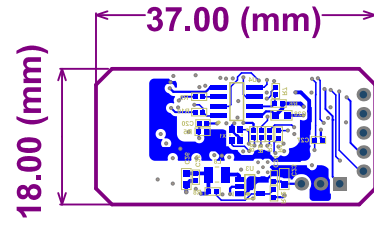




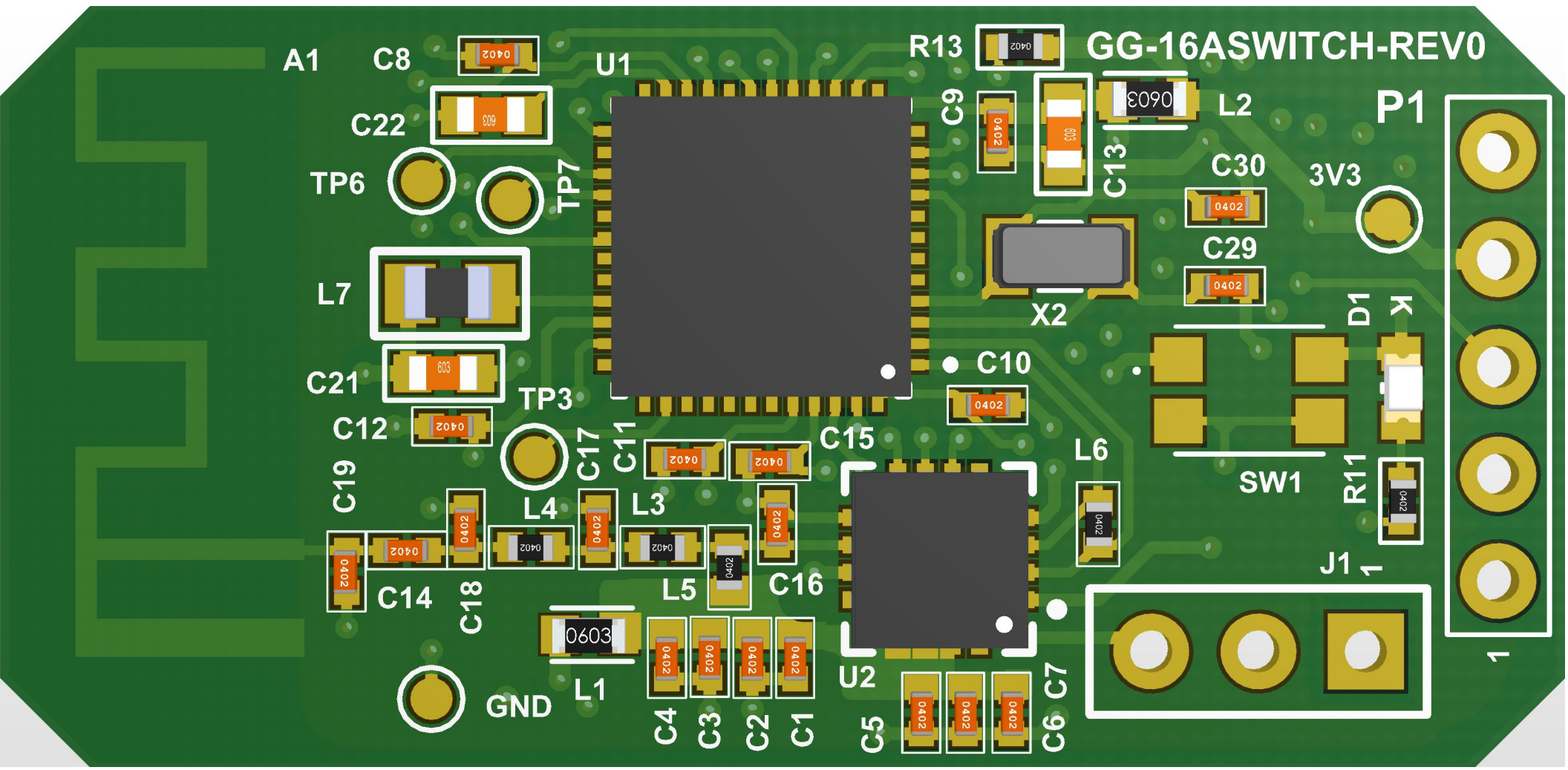




Signal Layer 2



Bottom Layer



GG-16ASWITCH-REV0

A1

C8

U1

R13

L2

P1

C22

TP6

TP7

C9

C30

3V3

L7

X2

C29

D1

C21

TP3

C10

K

C12

C17

C15

L6

SW1

R11

C19

L4

L3

C16

G1

J1

C14

C18

L5

C4

C3

C2

C1

C5

C7

GND

L1

C4

C3

C2

C1

U2

C6

C7

1

